



# HMBT5551

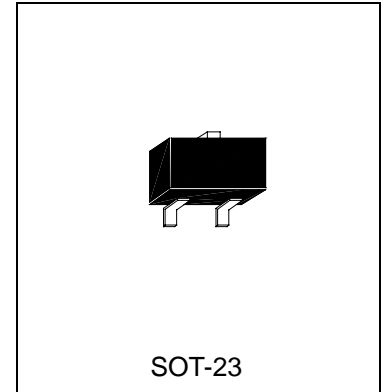
NPN EPITAXIAL PLANAR TRANSISTOR

## Description

The HMBT5551 is designed for general purpose applications requiring high Breakdown Voltages.

## Absolute Maximum Ratings

- Maximum Temperatures  
 Storage Temperature ..... -55 + 150 °C  
 Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation  
 Total Power Dissipation (Ta=25°C) ..... 225 mW
- Maximum Voltages and Currents (Ta=25°C)  
 VCBO Collector to Base Voltage ..... 180 V  
 VCEO Collector to Emitter Voltage..... 160 V  
 VEBO Emitter to Base Voltage..... 6 V  
 IC Collector Current..... 600 mA



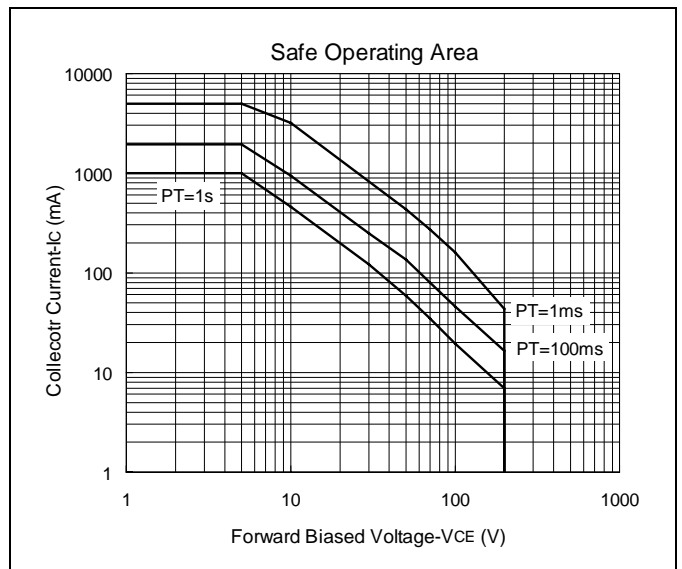
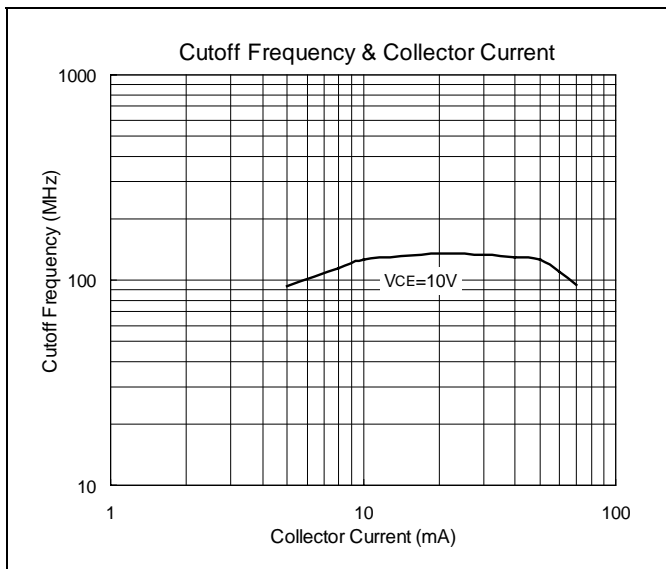
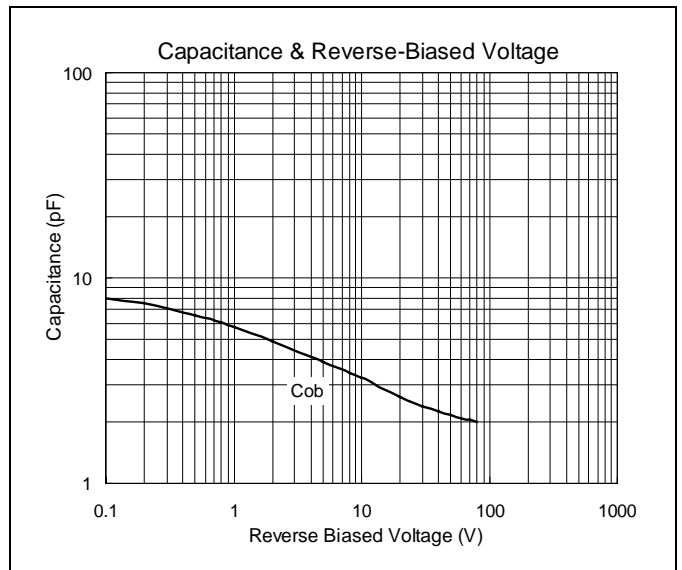
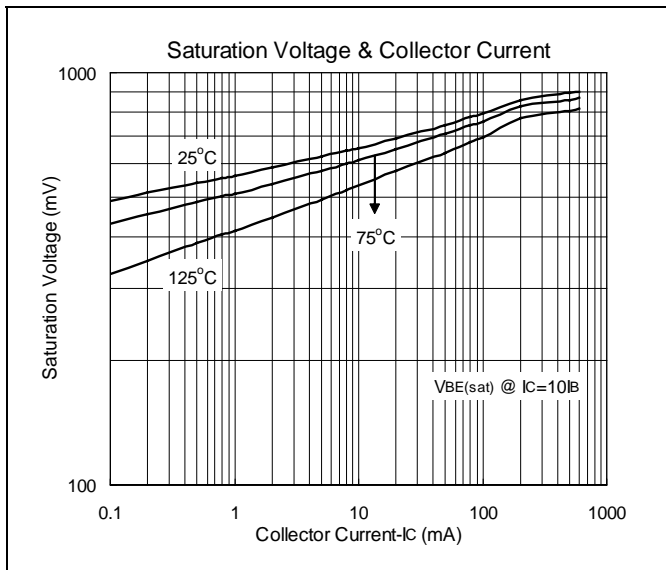
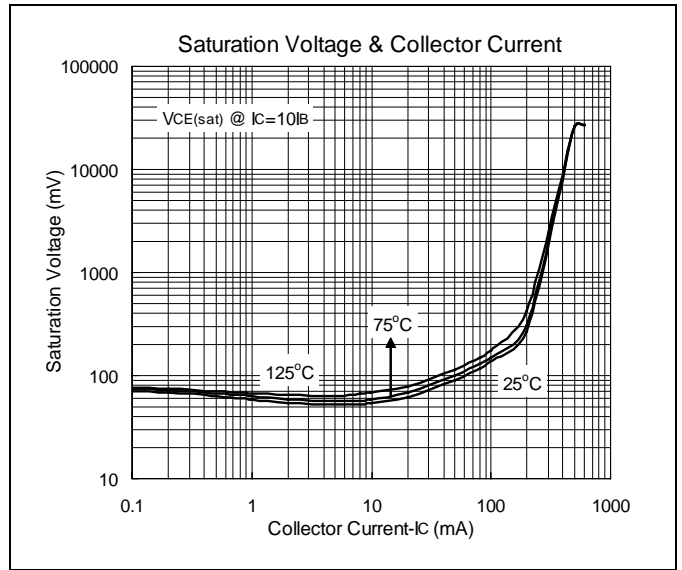
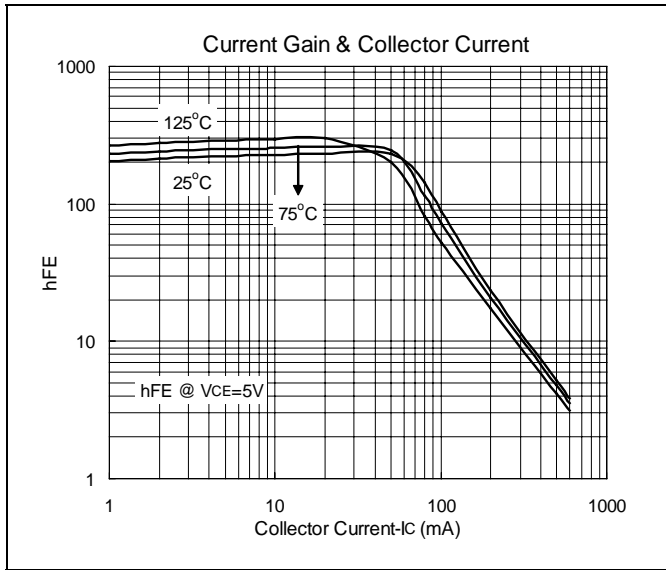
## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	180	-	-	V	IC=100uA
BVCEO	160	-	-	V	IC=1.0mA
BVEBO	6	-	-	V	IE=10uA
ICBO	-	-	50	nA	VCB=120V
IEBO	-	-	50	nA	VEB=4V
*VCE(sat)1	-	-	0.15	V	IC=10mA, IB=1.0mA
*VCE(sat)2	-	-	0.2	V	IC=50mA, IB=5mA
*VBE(sat)1	-	-	1	V	IC=10mA, IB=1mA
*VBE(sat)2	-	-	1	V	IC=50mA, IB=5mA
*hFE1	80	-	-		VCE=5V, IC=1mA
*hFE2	80	-	250		VCE=5V, IC=10mA
*hFE3	30	-	-		VCE=5V, IC=50mA
fT	100	-	300	MHz	IC=10mA, VCE=10V, f=100MHz
Cob	-	-	6	pF	VCB=10V, f=1MHz

\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

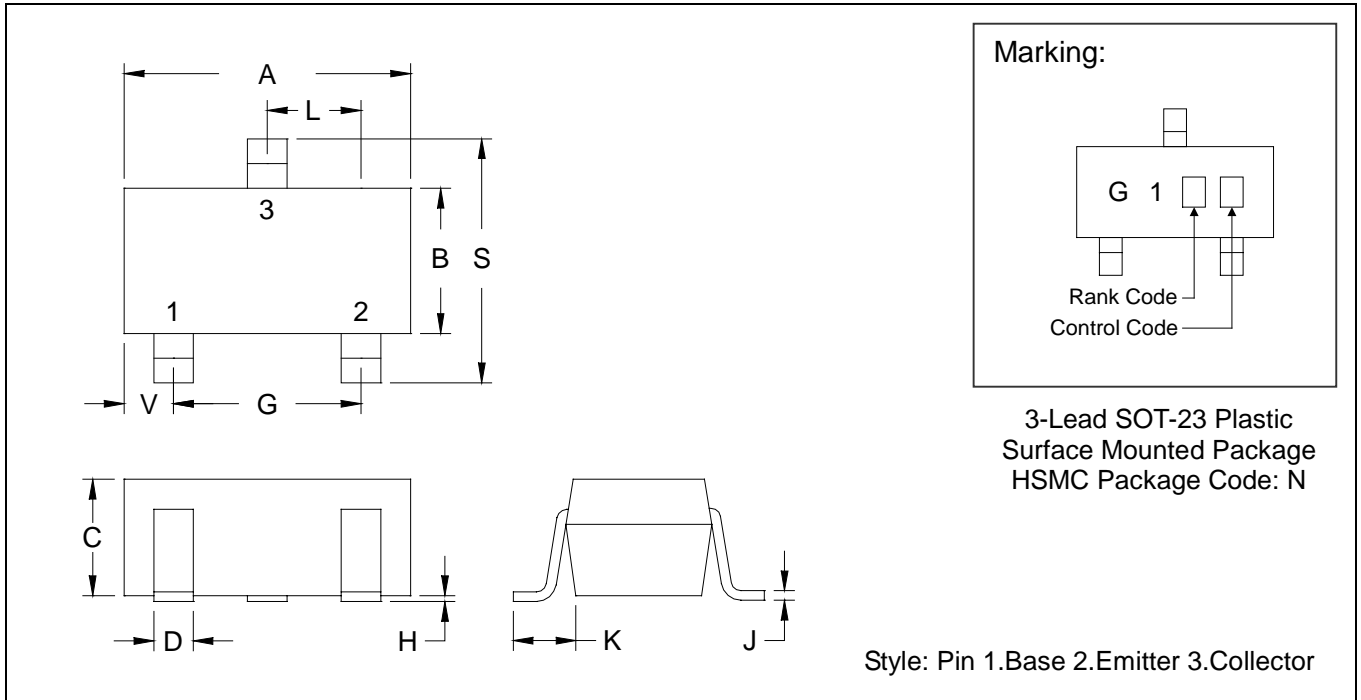


### Characteristics Curve





### SOT-23 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0034	0.0070	0.085	0.177
B	0.0472	0.0630	1.20	1.60	K	0.0128	0.0266	0.32	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1083	2.10	2.75
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0005	0.0040	0.013	0.10					

- Notes: 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.  
 2.Controlling dimension: millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

**Important Notice:**

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

**Head Office And Factory:**

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.  
 Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C  
 Tel: 886-3-5983621~5 Fax: 886-3-5982931



LittleDiode supplies new, hard to find or obsolete electronic components and semiconductors all over the world.

With over two million different components listed you are sure to find the part you need.

Feel free to visit us today at our online store:

[LittleDiode.com](http://LittleDiode.com)

Looking forward to providing you with the best possible service.